

Electronic Patent Application Fee Transmittal

Application Number:	10750059			
Filing Date:	30-Dec-2003			
Title of Invention:	SOLDER BALL PAD STRUCTURE			
First Named Inventor/Applicant Name:	Hiroshi Miyazaki			
Filer:	Yingsheng Tung/Jackie McBride			
Attorney Docket Number:	TI-36833			
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Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1440	1440
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Extension-of-Time:				
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Total in USD (\$)				1740